DISCRETE SEMICONDUCTORS

DATA SHEET

PDTA144W series PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 22 k Ω

Product specification Supersedes data of 2004 Mar 23 2004 Aug 05





PDTA144W series

FEATURES

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- · General purpose switching and amplification
- · Inverter and interface circuits
- Circuit driver.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	_	-50	V
I _O	output current (DC)	_	-100	mA
R1	bias resistor	47	_	kΩ
R2	bias resistor	22	_	kΩ

DESCRIPTION

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

PRODUCT OVERVIEW

TYPE NUMBER	PACE	KAGE	MARKING CODE	NDN COMPLEMENT	
TIFE NOMBER	PHILIPS	EIAJ	MARKING CODE	NPN COMPLEMENT	
PDTA144WE	SOT416	SC-75	5D	PDTC144WE	
PDTA144WEF	SOT490	SC-89	2E	PDTC144WEF	
PDTA144WK	SOT346	SC-59	46	PDTC144WK	
PDTA144WM	SOT883	SC-101	F8	PDTC144WM	
PDTA144WS	SOT54 (TO-92)	SC-43	TA144W	PDTC144WS	
PDTA144WT	SOT23	_	*43 ⁽¹⁾	PDTC144WT	
PDTA144WU	SOT323	SC-70	*28(1)	PDTC144WU	

Note

^{1. * =} p: Made in Hong Kong.

^{* =} t: Made in Malaysia.

^{* =} W: Made in China.

PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 22 k Ω

PDTA144W series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL	PINNING		
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION	
PDTA144WS	R1	1 2 3	base collector emitter	
PDTA144WE PDTA144WEF PDTA144WK PDTA144WT PDTA144WU	3 1 R1 R2 2 Top view MDB271	1 2 3	base emitter collector	
PDTA144WM	2 R1 3 Bottom view MDB267	1 2 3	base emitter collector	

PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 22 k Ω

PDTA144W series

ORDERING INFORMATION

TYPE NUMBER		PACKAGE	
I TPE NUMBER	NAME	DESCRIPTION	VERSION
PDTA144WE	_	 plastic surface mounted package; 3 leads 	
PDTA144WEF	DTA144WEF – plastic surface mounted package; 3 leads		SOT490
PDTA144WK	_	 plastic surface mounted package; 3 leads 	
PDTA144WM	_	leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm	SOT883
PDTA144WS	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTA144WT	 plastic surface mounted package; 3 leads 		SOT23
PDTA144WU	_	plastic surface mounted package; 3 leads	SOT323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-50	V
V _{CEO}	collector-emitter voltage	open base	_	-50	V
V _{EBO}	emitter-base voltage	open collector	_	-10	V
VI	input voltage				
	positive		_	+10	V
	negative		_	-40	V
Io	output current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C;			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	T _{amb} ≤ 25 °C		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT416	note 1	830	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

Note

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions.; FR4 with 60 μ m copper strip line.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0 \text{ A}$	_	_	-100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_{B} = 0 \text{ A}$	_	_	-1	μΑ
		$V_{CE} = -30 \text{ V}; I_{B} = 0 \text{ A}; T_{j} = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_{C} = 0 \text{ A}$	_	_	-110	μΑ
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -5 \text{ mA}$	60	_	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	_	-150	mV
$V_{i(off)}$	input-off voltage	$I_C = -100 \mu\text{A}; V_{CE} = -5 \text{V}$	_	-1.7	-1.2	V
V _{i(on)}	input-on voltage	$I_C = -2 \text{ mA}; V_{CE} = -0.3 \text{ V}$	-4	-2.7	_	V
R1	input resistor		33	47	61	kΩ
R2 R1	resistor ratio		0.37	0.47	0.57	
C _c	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = -10 \text{ V};$ f = 1 MHz	_	_	3	pF

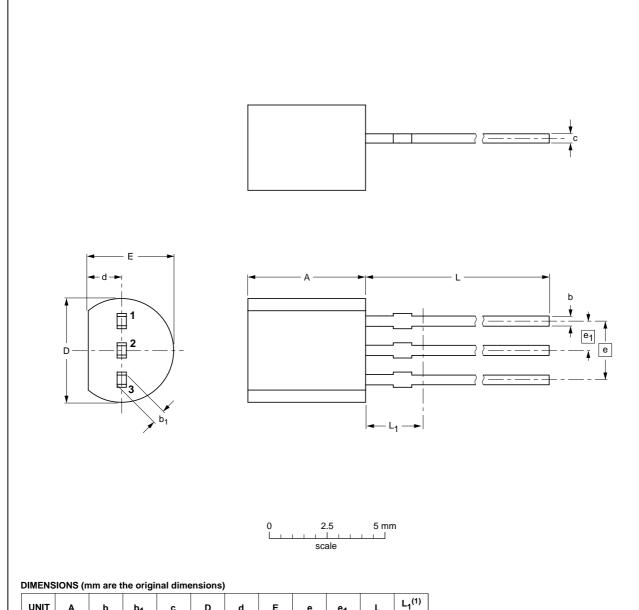
PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 22 k Ω

PDTA144W series

PACKAGE OUTLINES

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b ₁	С	D	d	E	е	e ₁	L	L ₁ ⁽¹⁾ max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

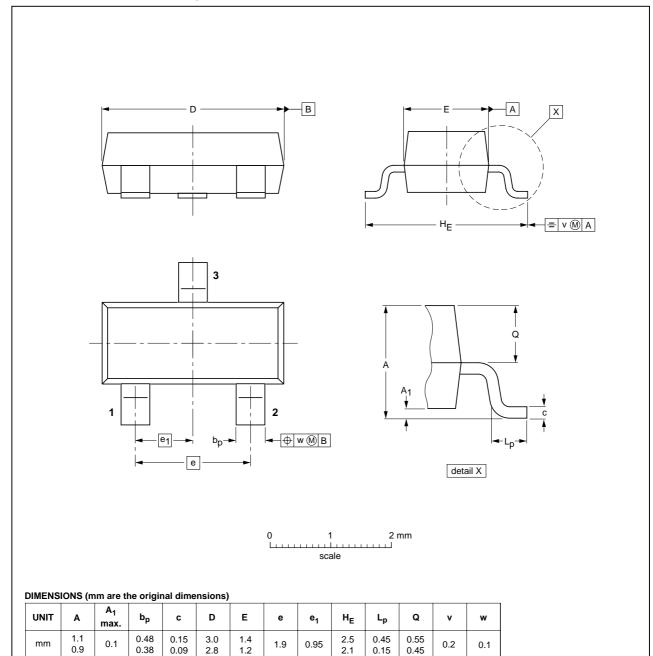
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	155UE DATE	
SOT54		TO-92	SC-43A		97-02-28 04-06-28	

PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 22 k Ω

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Plastic surface mounted package; 3 leads

SOT23

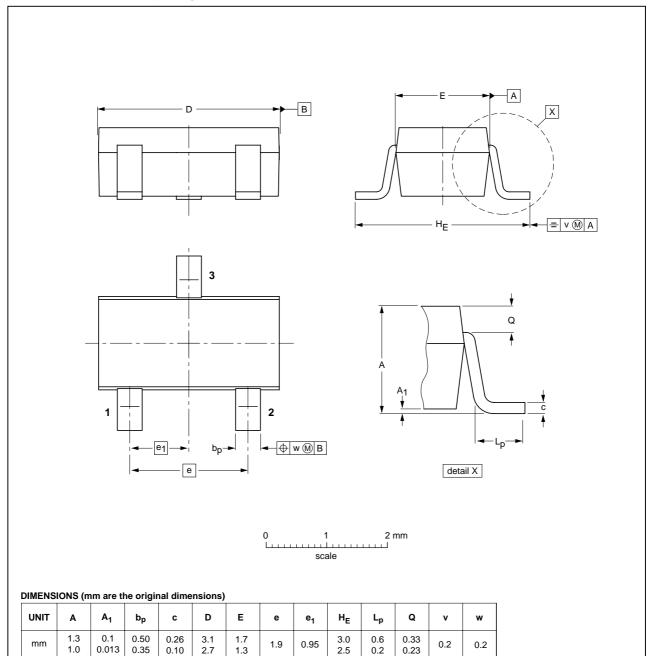


OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT23		TO-236AB			-97-02-28- 99-09-13	

PDTA144W series

Plastic surface mounted package; 3 leads

SOT346



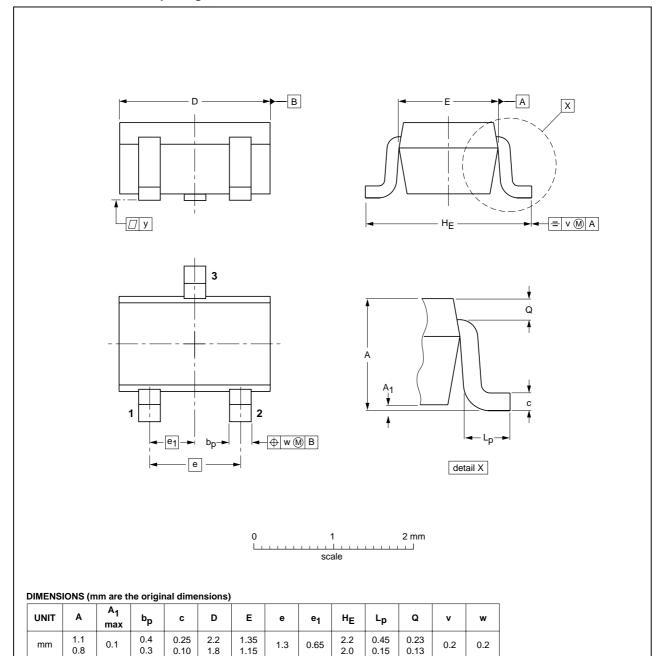
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT346		TO-236	SC-59		98-07-17

PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 22 k Ω

PDTA144W series

Plastic surface mounted package; 3 leads

SOT323

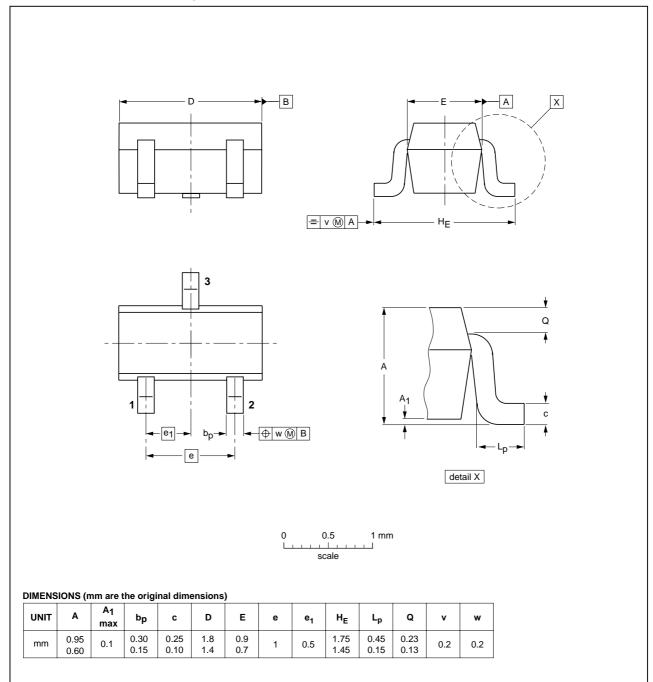


OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT323			SC-70		97-02-28

PDTA144W series

Plastic surface mounted package; 3 leads

SOT416

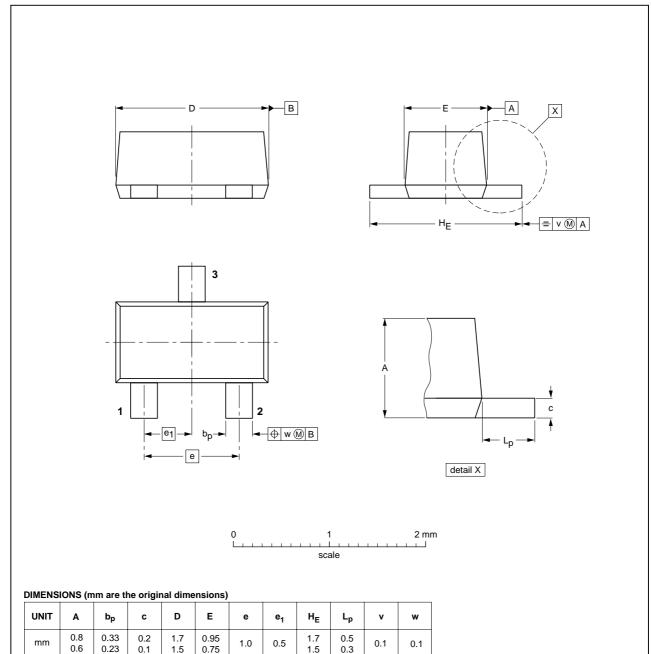


OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT416			SC-75			97-02-28

PDTA144W series

Plastic surface mounted package; 3 leads

SOT490



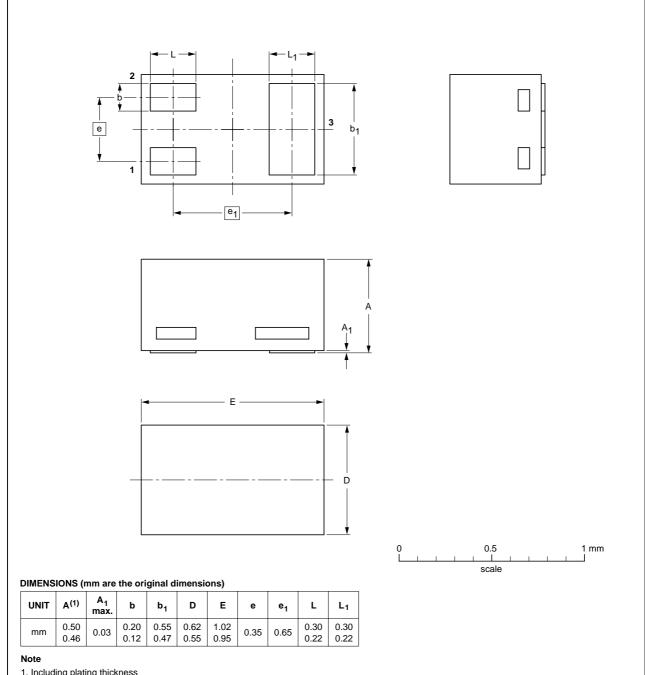
OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT490			SC-89		$\bigoplus \bigoplus$	98-10-23

PNP resistor-equipped transistors; $R1 = 47 \text{ k}\Omega$, $R2 = 22 \text{ k}\Omega$

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Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883



1. Including plating thickness

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT883			SC-101			03-02-05 03-04-03

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PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 22 k Ω

PDTA144W series

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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